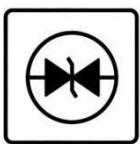




ESD



TVS



TSS



MOV



GDT



PLED

DSK32-MS THRU DSK310-MS

Product specification

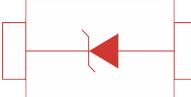
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- High forward surge current capability
- High temperature soldering guaranteed: 250°C/10 seconds, 0.375(9.5mm) lead length, 5 lbs. (2.3kg) tension

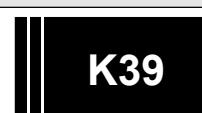
MECHANICAL DATA

- Case: JEDEC SOD-123FL molded plastic body over passivated junction
- Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.0007 ounce, 0.02 grams

Reference News

SOD-123FL	Schematic Diagram
	

Marking

DSK32-MS	DSK33-MS	DSK34-MS	DSK35-MS	DSK36-MS
				
DSK37-MS	DSK38-MS	DSK39-MS	DSK310-MS	
				

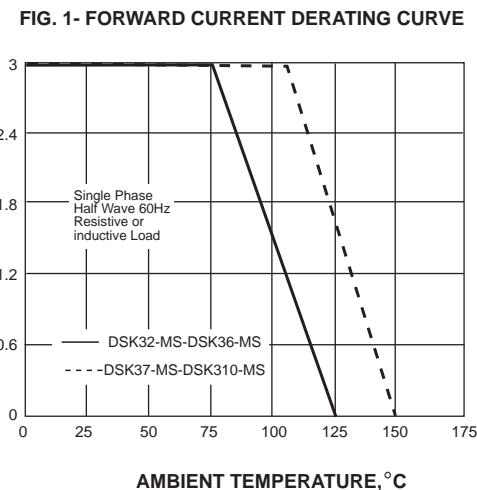
Maximum Ratings and Electrical Characteristics TA = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

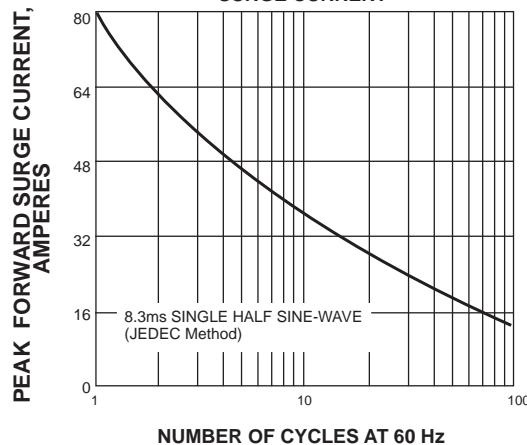
Characteristic	Symbol	DSK32-MS	DSK33-MS	DSK34-MS	DSK35-MS	DSK36-MS	DSK37-MS	DSK38-MS	DSK39-MS	DSK310-MS	Unit		
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	70	80	90	100	Volts		
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	49	56	63	70	Volts		
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	70	80	90	100	Volts		
Maximum average forward rectified current	I _(AV)	3.0								Amp			
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	80.0								Amps			
Maximum instantaneous forward voltage at 3.0A	V _F	0.52	0.55	0.70	0.85				Volts				
Maximum DC reverse current TA=25°C at rated DC blocking voltage TA=100°C	I _R	0.5							mA				
		20.0				10.0							
Operating junction temperature range	T _J	-50 to +125				-50 to +150				°C			
Storage temperature range	T _{STG}	-50 to +150								°C			

RATINGS AND CHARACTERISTIC CURVES DSK32-MS THRU DSK310-MS

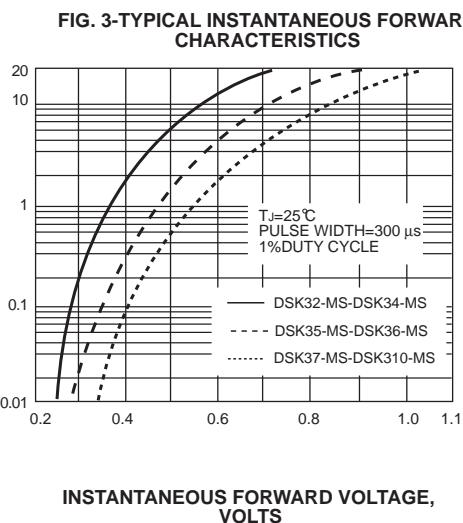
AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES



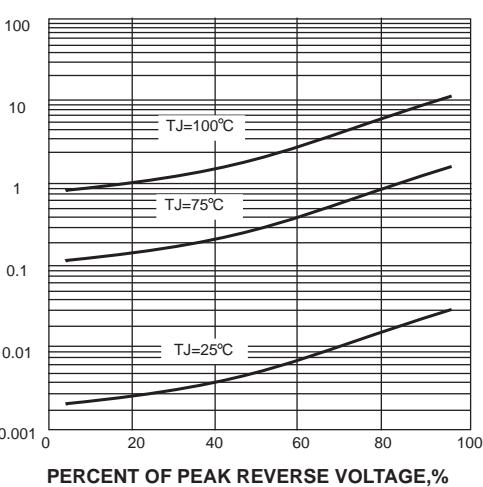
PEAK FORWARD SURGE CURRENT,
AMPERES



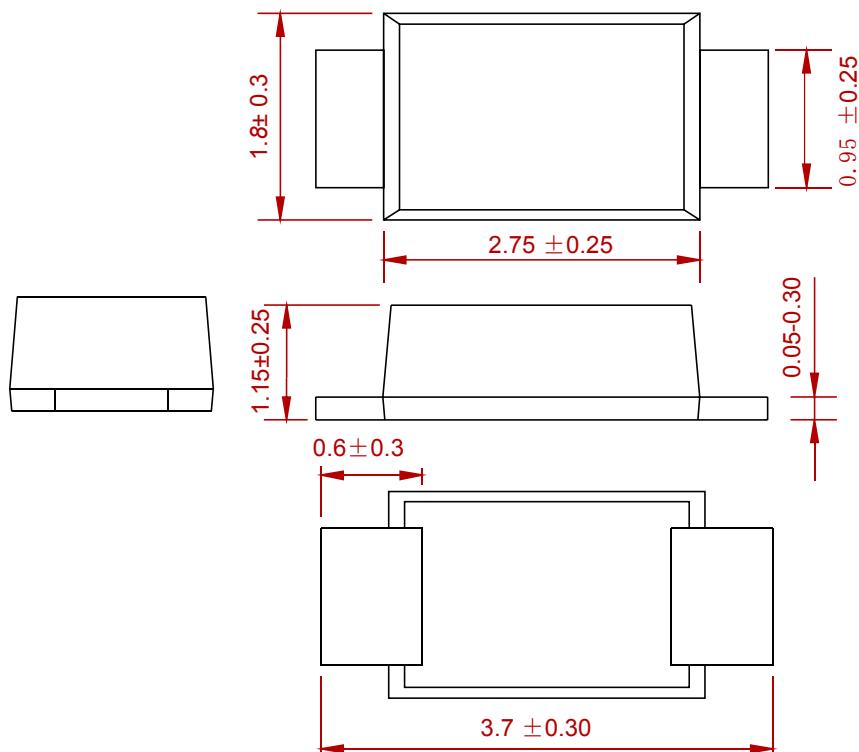
INSTANTANEOUS FORWARD CURRENT, AMPERES



INSTANTANEOUS REVERSE CURRENT,
MILLIAMPERES

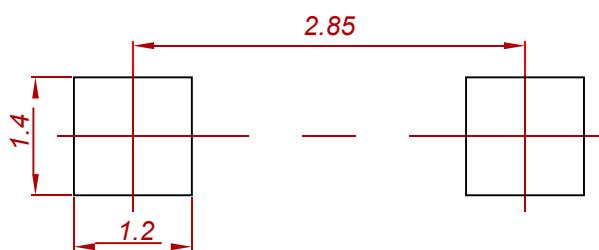


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
DSK32-MS THRU DSK310-MS	SOD-123FL	3000

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Reference News

PACKAGE OUTLINE	Schematic Diagram

Marking

DSS32-MS	DSS33-MS	DSS34-MS	DSS35-MS	DSS36-MS
DSS37-MS	DSS38-MS	DSS39-MS	DSS310-MS	

Maximum Ratings and Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise specified

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